



Material Content Data Sheet



Sales Product Name	TLS850B0TB V50			Issued		4. February 2020		
MA#	MA002031348							
Package	PG-TO263-5-1			Weight*		1670.92 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.422	0.09	0.09	851	851
leadframe	inorganic material	phosphorus	7723-14-0	0.145	0.01		87	
	non noble metal	iron	7439-89-6	0.483	0.03		289	
	non noble metal	copper	7440-50-8	482.096	28.85	28.89	288522	288898
wire	non noble metal	aluminium	7429-90-5	0.358	0.02	0.02	214	214
encapsulation	organic material	carbon black	1333-86-4	1.461	0.09		874	
	plastics	epoxy resin	-	67.183	4.02		40207	
	inorganic material	silicondioxide	60676-86-0	661.607	39.59	43.70	395952	437033
leadfinish	non noble metal	tin	7440-31-5	12.370	0.74	0.74	7403	7403
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1	
	non noble metal	nickel	7440-02-0	0.243	0.01	0.01	145	146
solder	non noble metal	tin	7440-31-5	0.030	0.00		18	
	noble metal	silver	7440-22-4	0.038	0.00		23	
	non noble metal	lead	7439-92-1	1.456	0.09	0.09	871	912
heatspreader	inorganic material	phosphorus	7723-14-0	0.133	0.01		79	
	non noble metal	iron	7439-89-6	0.442	0.03		265	
	non noble metal	copper	7440-50-8	441.456	26.42	26.46	264199	264543
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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